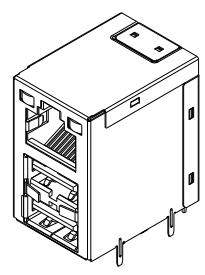
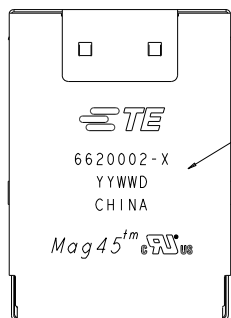


8	7	6	5	4	3	2	1
TE CONNECTIVITY	TE CONNECTIVITY	TE CONNECTIVITY	TE CONNECTIVITY	TE CONNECTIVITY	TE CONNECTIVITY	TE CONNECTIVITY	TE CONNECTIVITY

REV	DATE	DESCRIPTION	BY	CHK	APP
0	10-01-2013		EDM/SH	BO	AZ
1	10-11-2014		DM/SH	PP	LS



SCALE 3:1

- USB MATERIALS:**
 SHELL - BRASS, PLATED WITH TIN 2.54µ MIN
 HOUSING - BLACK, THERMOPLASTIC, GLASS FILLED, UL 94V-0 RATED
 CONTACT - PHOSPHOR BRONZE WITH SELECTIVE GOLD PLATING

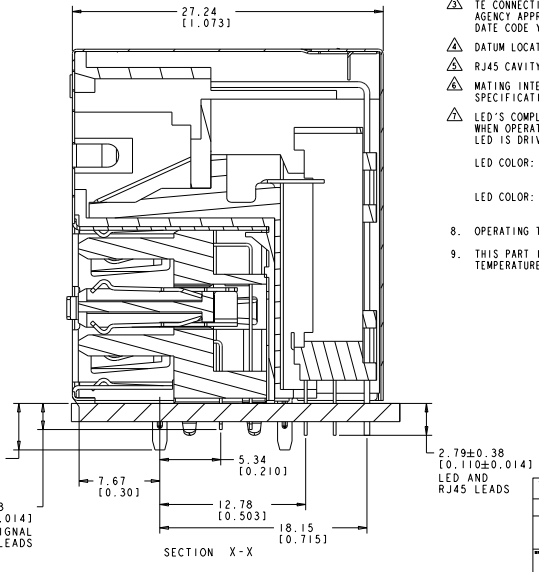
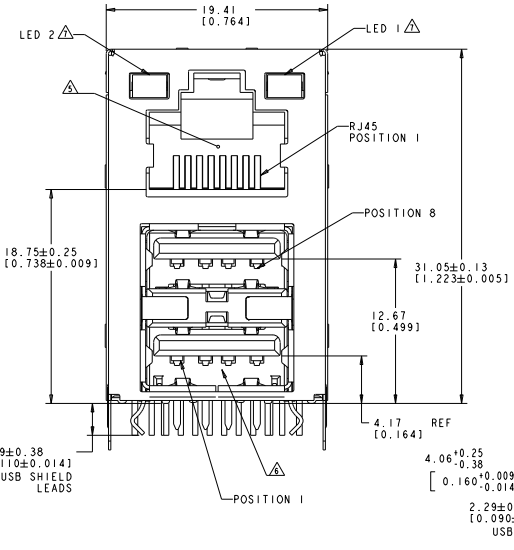
RJ45 MATERIALS:
 PLASTIC HOUSING - BLACK, PET THERMOPLASTIC FLAMMABILITY RATING UL 94V-0
 SHIELD - BRASS, PLATED WITH 1.27µ SEMI-BRIGHT (SATIN) NICKEL,
 SELECT TIN, 2.0-3.8µ ON SOLDER TAILS ONLY
 CONTACTS: PHOSPHOR BRONZE
 PLATING: 1.27µ MIN NICKEL UNDER PLATE WITH SELECT 0.76µ MIN GOLD AT MATING
 SELECT INTERFACE AND 2.54µ MIN TIN ON CONTACT TAILS

 LED - DIFFUSED EPOXY LENS, CARBON STEEL LEAD FRAME WITH TIN/SILVER/NICKEL/
 COPPER PLATING

MAGNETICS:
 APPLICATION: 10/100 BASE-T
 IMPEDANCE: 100 OHMS
 TURNS RATIO (CHIP-CABLE): TX = 1:1, RX = 1:1
 OPEN CIRCUIT INDUCTANCE (OCL): 350nH MIN @100kHz, 0.1VRMS,
 8mADC BIAS FROM 0°C TO 70°C, TX AND RX
 PERFORMANCE @ 25°C:
 INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 12dB MIN FROM 60.1MHz TO 80MHz
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 33-20LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 ISOLATION VOLTAGE: COMPLIES WITH IEEE802.3 2002, PARA 23.5.1.1, ITEM b.

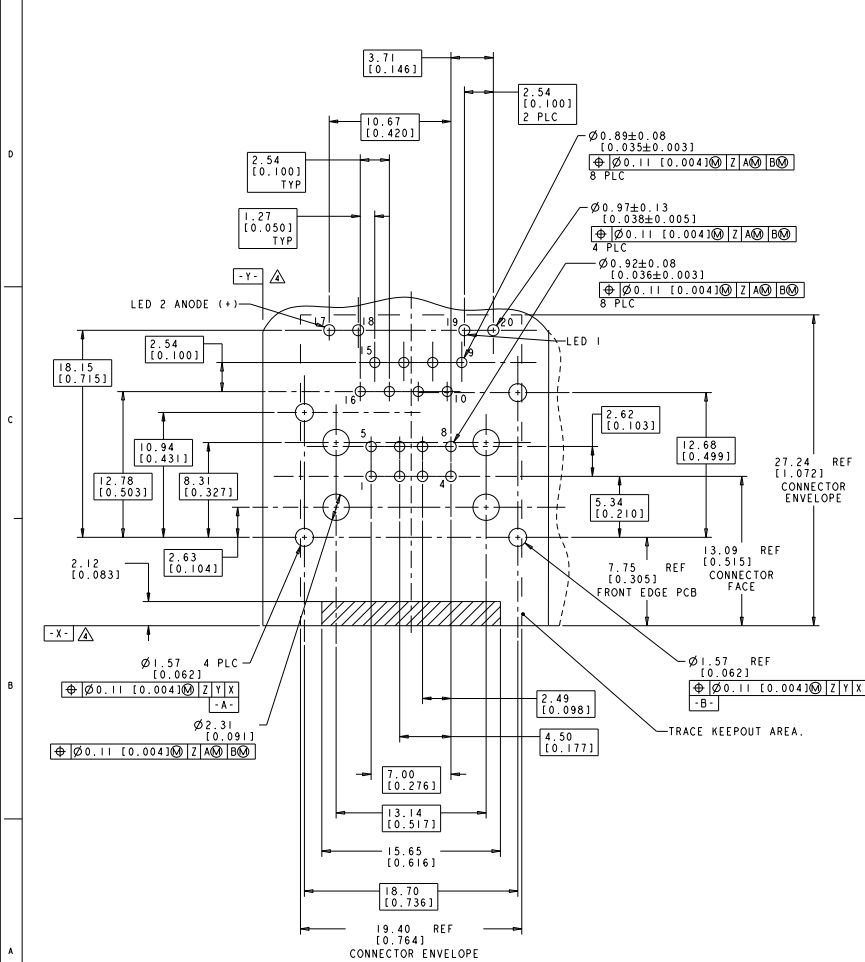
**TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND
 AGENCY APPROVAL MARKING LOGO LOCATED IN THE APPROXIMATE AREA SHOWN.
 DATE CODE YY IS YEAR, WW IS WORK WEEK, D IS DAY OF WEEK, WITH SUNDAY=1.**

DATUM LOCATION AND DIMENSION TO BE ESTABLISHED BY CUSTOMER
RJ45 CAVITY CONFORMS TO FCC RULES AND REGULATION PART 68 SUPPORT F
**MATING INTERFACE COMPLIES WITH USB (UNIVERSAL SERIAL BUS)
 SPECIFICATION REV. 1.0**
**LED'S COMPLIANT WITH IEC60825-1 SAFETY OF LASER PRODUCTS
 WHEN OPERATED UP TO CURRENT OF 20 mA MAX.
 LED IS DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA.**
 LED COLOR: DOMINANT WAVELENGTH (λD): GREEN 565 nm TYP @ VF=5V
 FORWARD CURRENT (IF): GREEN 12 mA TYP @ VF=5V
 LED COLOR: DOMINANT WAVELENGTH (λD): YELLOW 585 nm TYP @ VF=5V
 FORWARD CURRENT (IF): YELLOW 13 mA TYP @ VF=5V
- OPERATING TEMPERATURE: FROM 0°C TO +70°C.
- THIS PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PEAK SOLDERING TEMPERATURE IS 260 °C MAX, 10 SECONDS MAX.



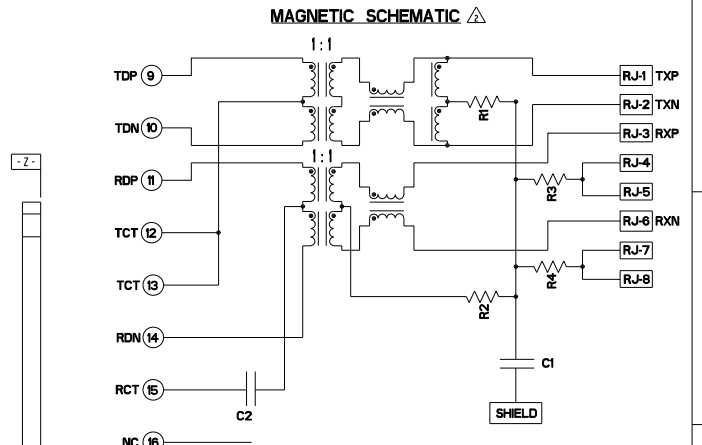
GREEN	GREEN/YELLOW	6620002-1
LED 2	LED 1	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		TE CONNECTIVITY	
REV	DATE	DESCRIPTION	BY
0	10-01-2013		EDM/SH
1	10-11-2014		DM/SH
REV	DATE	DESCRIPTION	BY
0	10-01-2013		EDM/SH
1	10-11-2014		DM/SH
REV	DATE	DESCRIPTION	BY
0	10-01-2013		EDM/SH
1	10-11-2014		DM/SH
REV	DATE	DESCRIPTION	BY
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1	10-11-2014		DM/SH

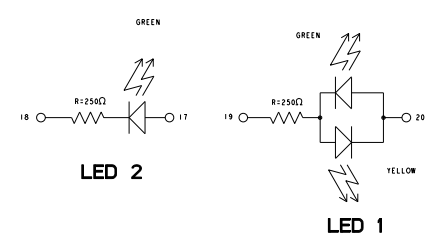


RECOMMENDED P.C.B. FOOTPRINT
COMPONENT SIDE

REVISEMENTS		DATE	BY	CHK
AA	00			



R1 - R4 = 75 OHMS, 1/16W, 5% RESISTORS
C1 = 1000pF, 2kV DECOUPLING CAPACITOR
C2 = 0.1uF, 10%, 50V, X7R CAPACITORS



THIS DRAWING IS A CONTROLLED DOCUMENT.		REV. 1	DATE 01/15/2008	BY	TE Connectivity
APPROVED	DESIGNED	DATE	BY	REVISED	DESCRIPTION
					RJ45 OVER DUAL USB_MAG45_TM 10/100 WITH RESISTOR LEADS
DATE	BY	DATE	BY	DATE	DESCRIPTION
01/15/2008	AA	01/15/2008	AA	01/15/2008	AA
NOTE 1	SEE	NOTE 1	SEE	NOTE 1	SEE